

ABSTRACT OF THE DISCLOSURE

Semiconductor wire bonding tools used in the assembly and interconnection of integrated circuits (ICs) are micromolded from a mixture of ultrafine particulate materials mixed with an organic binder. Following extraction of the binder the green bonding tools are sintered during which they undergo isotropic, constant and accurately predetermined shrinkage. Hence semiconductor wire bonding tools can be produced with virtually no limit to miniaturization, thus allowing the fabrication of higher integrated semiconductor products.